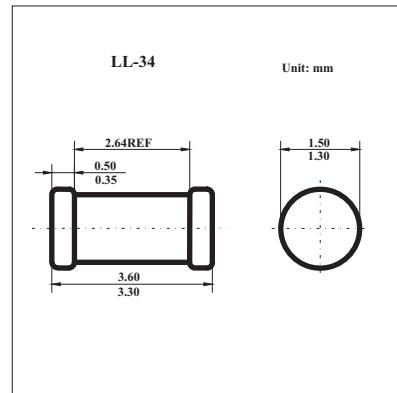


## High-speed diode

### BAS32L

#### ■ Features

- Small hermetically sealed glass SMD package
- High switching speed: max. 4 ns
- Continuous reverse voltage: max. 75 V
- Repetitive peak reverse voltage: max. 75 V
- Repetitive peak forward current: max. 450 mA.



#### ■ Absolute Maximum Ratings Ta = 25°C

Parameter	Symbol	Rating	Unit
continuous reverse voltage	V <sub>R</sub>	75	V
continuous forward current	I <sub>F</sub>	200	mA
repetitive peak forward current	I <sub>FRM</sub>	450	mA
non-repetitive peak forward current t = 1 μ s		4	
t = 1 ms	I <sub>FSM</sub>	1	A
t = 1 s		0.5	
total power dissipation	P <sub>D</sub>	500	mW
thermal resistance from junction to tie-point	R <sub>th j-tp</sub>	300	K/W
thermal resistance from junction to ambient	R <sub>th j-a</sub>	350	K/W
junction temperature	T <sub>j</sub>	200	°C
storage temperature	T <sub>stg</sub>	-65 to +200	°C

#### ■ Electrical Characteristics Ta = 25°C

Parameter	Symbol	Testconditons	Min.	Max	Unit
forward voltage	V <sub>F</sub>	I <sub>F</sub> = 5 mA I <sub>F</sub> = 100 mA I <sub>F</sub> = 100 mA; T <sub>j</sub> =100°C	620	750 1000 930	mV
reverse current	I <sub>R</sub>	V <sub>R</sub> = 20 V V <sub>R</sub> = 75 V V <sub>R</sub> = 20 V; T <sub>j</sub> = 150°C V <sub>R</sub> = 75 V; T <sub>j</sub> = 150°C		25 5 50 100	nA μ A μ A μ A
reverse breakdown voltage	V <sub>(BR)R</sub>	I <sub>R</sub> = 100 μ A	100		V
diode capacitance	C <sub>d</sub>	f = 1 MHz; V <sub>R</sub> = 0V		2	pF
reverse recovery time	t <sub>rr</sub>	when switched from I <sub>F</sub> = 10 mA to I <sub>R</sub> = 10 mA; R <sub>L</sub> = 100 Ω ;measured at I <sub>R</sub> = 1 mA		4	ns
forward recovery voltage	V <sub>fr</sub>	when switched from I <sub>F</sub> = 50 mA;t <sub>r</sub> = 20 ns;		2.5	V

\* Pulsed test: t<sub>p</sub> = 300 μs; δ = 0.02.